# Zibo Seno Electronic Engineering Co., Ltd.



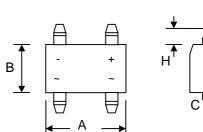
**ABS05 – ABS10** 

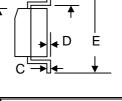


0.5A SURFACE MOUNT GLASS PASSIVATED BRIDGE RECTIFIER

### Features

- Glass Passivated Die Construction
- Low Forward Voltage Drop
- High Current Capability
- High Surge Current Capability
- Designed for Surface Mount Application
- Plastic Material UL Flammability 94V-O

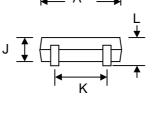




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#### **Mechanical Data**

- Case: SOPA-4, ABS, Molded Plastic
- Terminals: Plated Leads Solderable per
- MIL-STD-202, Method 208
  Polarity: As Marked on Case
- Mounting Position: Any
- Marking: Type Number
- Lead Free: For RoHS / Lead Free Version



ABS								
Dim	Min	Max						
Α	4.80	5.30						
В	4.20	4.60						
С	0.15	0.25						
D	—	0.20						
Е	6.00	6.80						
G	0.30	0.70						
н	0.90	1.10						
J		1.50						
К	3.80	4.20						
L	1.22	1.72						
All Dimensions in mm								

## Maximum Ratings and Electrical Characteristics @TA=25°C unless otherwise specified

Single Phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Characteristic	Symbol	ABS05	ABS1	ABS2	ABS4	ABS6	ABS8	ABS10	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	Vrrm Vrwm Vr	50	100	200	400	600	800	1000	V
RMS Reverse Voltage	VR(RMS)	35	70	140	280	420	560	700	V
Average Rectified Output Current (Note 1) $@T_A = 40^{\circ}C$ Average Rectified Output Current (Note 2) $@T_A = 40^{\circ}C$	lo	0.5 0.8							А
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	IFSM	30							A
$I^{2}t$ Rating for Fusing (t < 8.3ms)	l <sup>2</sup> t	5.0						A <sup>2</sup> s	
Forward Voltage per element $@I_F = 0.5A$	VFM	1.0						V	
Peak Reverse Current $@T_A = 25^{\circ}C$ At Rated DC Blocking Voltage $@T_A = 125^{\circ}C$	<b>I</b> RM	5.0 500						μΑ	
Typical Junction Capacitance per leg (Note 3)	Cj	13						pF	
Typical Thermal Resistance per leg (Note 1)	R∂JA R∂JL	62.5 20						°C/W	
Operating and Storage Temperature Range	Тј, Тѕтс	-55 to +150							°C

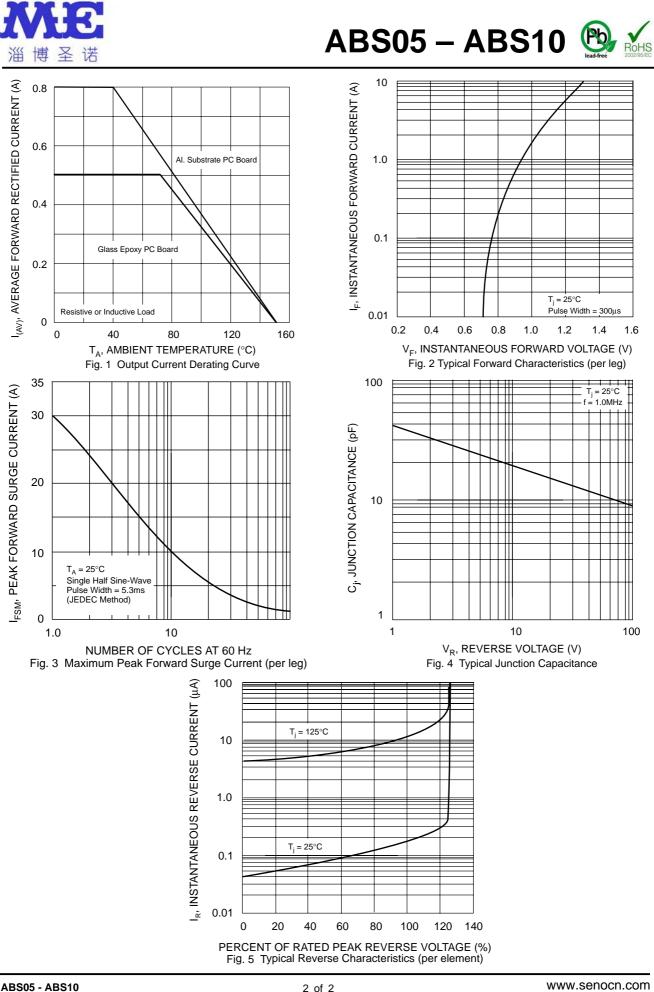
Note: 1. Mounted on glass epoxy PC board with 1.3mm<sup>2</sup> solder pad.

2. Mounted on aluminum substrate PC board with 1.3mm<sup>2</sup> solder pad.

3. Measured at 1.0 MHz and applied reverse voltage of 4.0V D.C.

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Alldatasheet